

D1711VHR Class 1 Laser information

D1711VHR-09C-000111 are classified as Class 1 Laser products per IEC 60825-1 Ed. 3. These devices comply with 21 CFR 1040.10 and 1040.11, except for conformance with IEC 60825-1 Ed. 3.Caution:These devices contain one or more lasers. Using, repairing, or disassembling devices not specified in the user manual may cause damage, which could result in hazardous emission of red light VCSEL.

CLASS 1 LASER PRODUCT

Harvatek Surface Mount CHIP VCSEL LEDs Data Sheet D1711VHR-09C000111E0118

Official Product	HT Part No. D 1711VHR-09C000111E0118				
Tentative Product	*******				
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DISCLAIMER

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Life Support Policy

HARVATEK's products are not authorized for use as critical components in life support devices or systems without the express written approval of the President of HARVATEK or HARVATEK INTERNATIONAL. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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Product Specifications

Item	Specification	Material	Quantity
Peak Wavelength	Typ:667 nm		
λ_{p}	@9mA/ T_S = 25°C; Tolerance: \pm 1nm		
Radiometric Power	Typ:3 mW		
Ро	@9mA/ T _s = 25°C; Tolerance: <u>+</u> 10%		
Forward Voltage	1.6-2.8 V		
V _F	@9mA/ T_S = 25°C ;Tolerance: \pm 0.1V		
Reverse Current	< 10 μΑ		
I_R	@ V _R = 5 V		
Resin	Clear	Silicon	
Carrier tape	EIA 481-1A specs	Conductive black tape	
Reel	EIA 481-1A specs	Conductive black	
Label	HT standard	Paper	
Packing bag	250x230mm	Aluminum laminated bag/ no-zipper	One reel per bag
Carton	HT standard	Paper	Non-specified

Others:

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of Iv, λ_D and Vf. Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note: This is shipped test conditions

※Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

ATTENTION: Electrostatic Discharge (ESD) protection



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlGaInP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must

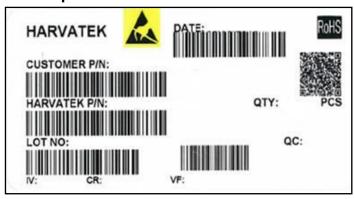
be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

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Label Specifications



■Harvatek P/N:

D 171 1 VHR- 09C- 0001 11

Product	Package	Dice Q' ty	Color	Current	Series Number	Taping
Ceramic+z	2.04(L)x1.64(W)x0.8(H)	1:Single	VHR: 667nm	9mA	X001~XZZZ	1.Taping style
ener	mm		VCSEL			2. Q'ty

■ Lot No.:

1 2	3	4	5	6	7	8	9	10
E 1	Α	1	Α	2	2	L	1	2
Code 1 2	Code 3	Code 4	Code 5	Code 6	Code 7	Code 8	Code 9	Code 10
	Mfg. Year	Mfg. Month	Mfg. Date	Consecuti	ve number		Special code	9
Internal Tracing Co	2020-L 2021-M 2022-P 2023-Q de 2026-T 2027-V 2030-Y 2031-Z	1:Jan. 2:Feb. A:Oct. B:Nov. C:Dec.	1:A 2:B 3:C 26:Z 27:7 28:8 29:9 30:3 31:4	01-	-ZZ		000~ZZZ	

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Absolute Maximum Rating at 25℃

Symbol	Parameters	Ratings	Units	Notes
I _F	Forward Current	9	mA	
I _{FP}	Peak Forward Current	20	mA	1
V _R	Reverse Voltage	5	V	
T _{opr}	Operating Temperature	-40 ~ +85	$^{\circ}\!\mathbb{C}$	
T _{stg}	Storage Temperature	-40 ~ +100	$^{\circ}\!\mathbb{C}$	
T _{sol}	Soldering Temperature	260	$^{\circ}\!\mathbb{C}$	2

Notes:

- 1. I_{FP} Conditions--Pulse Width≦100µs and Duty≦1%.
- $2. \hspace{0.5cm} \text{Soldering time} \! \leq \! 5 \text{ seconds}.$

Electro-Optical Characteristics

Symbol	Parameters	Test conditions	Min	Тур	Max	Units	Notes
Po	Radiometric Power	I _F =9mA	2	3	5	mW	3
λ _P	Peak Wavelength I _F =9mA		-	667	-	nm	5
Δλ	Spectral bandwidth at 50% of I _{max}	I _F =9mA		1	-	nm	
lth	Threshold Current			2.5		mA	
V_{F}	Forward Voltage	I _F =9mA	1.6	2.4	2.8	V	6
I _R	Reverse Current	V _R =5V	-	-	10	μA	
2θ _{1/2}	Angle of Half Intensity	I _F =9mA	-	20	-	deg	

Notes:

3. Radiometric Power (mW) Bin

Color	Bin Code	Spec. Range
	PC	2-3 mW
VHR	PD	3-4 mW
	PE	4-5 mW

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Notes:

4. Peak Wavelength (λ_P) Bin:

Color	Bin Code	Spec. Range
VHR	H2	655-675 nm

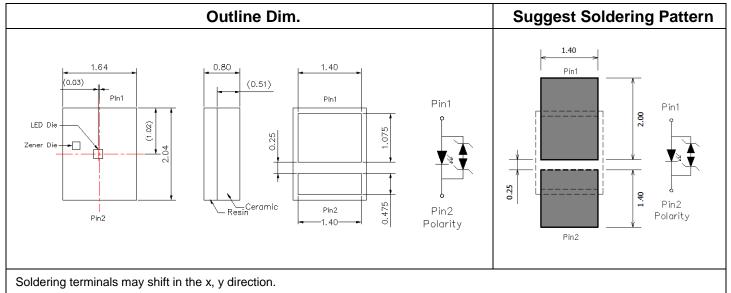
5. Forward Voltage (V_F) Bin:

Color	Bin Code	Spec. Range
	E5	1.6-1.8 V
	E6	1.8-2.0 V
VHR	F5	2.0-2.2 V
VIIIX	F6	2.2-2.4 V
	G5	2.4-2.6 V
	G6	2.6-2.8 V

(It maintains a tolerance of ±0.1V on forward voltage measurements)

Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

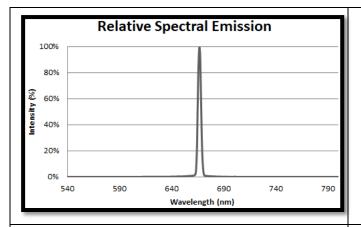
(Unit:mm Tolerance: +/-0.1)

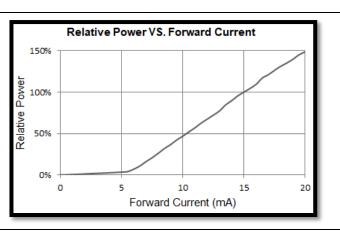


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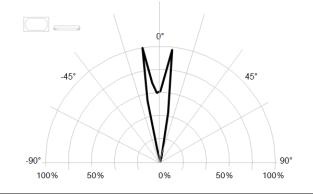


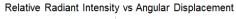
Characteristics of D1711VHR

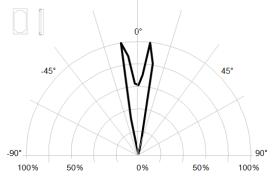


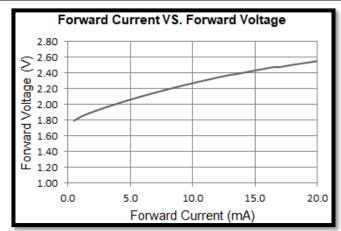


Relative Radiant Intensity vs Angular Displacement









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Precaution for Use

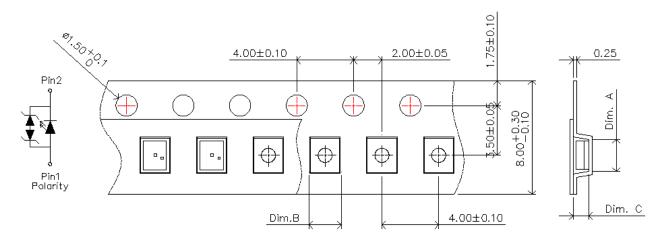
- 1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
- 2. When the VCSEL LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
- 3. VCSEL LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
- 4. The VCSEL LEDs must be used within 168 hrs after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
- 5. The appearance and specifications of the products may be modified for improvement without further notice.
- 6. The VCSEL LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the VCSEL LEDs .If a voltage over the absolute maximum rating is applied to VCSEL LEDs, it will damage VCSEL LEDs. Damaged VCSEL LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

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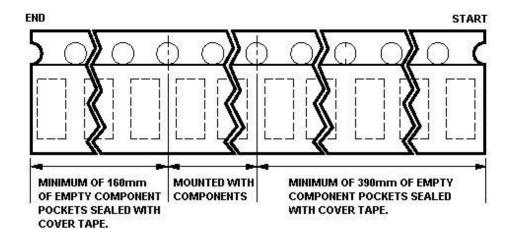


Packaging Tape Dimension

Top View Top Mount



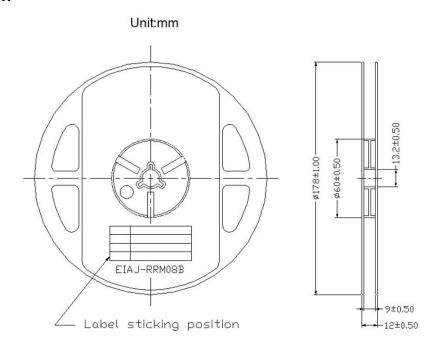
Dim. A	Dim. B	Dim. C	Q'ty/Reel
1.85+/-0.05	2.28+/-0.05	0.95+/-0.05	1K



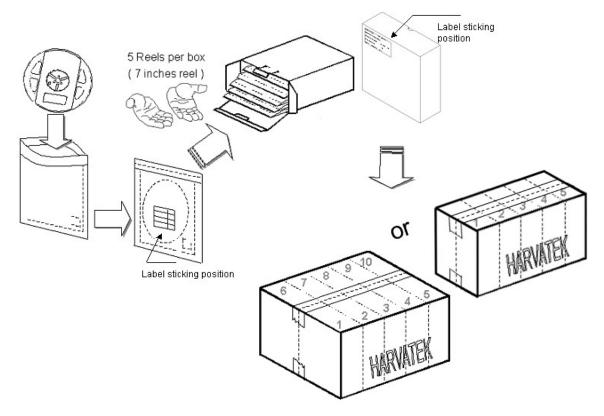
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Reel Dimension



Packing



5 or 10 boxes per carton is available depending on shipment quantity.

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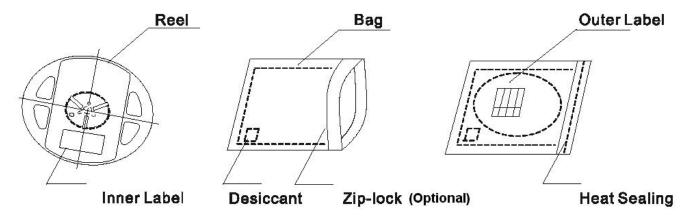


Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



Baking

Baking before soldering is recommended when the package has been unsealed for 168 hrs. The conditions are as followings:

- 1. 60 ± 3 °C×(12~24hrs)and<5%RH, taped reel type.
- 2. 100 ± 3 °C×(45min~1hr), bulk type.
- 3. $130\pm3^{\circ}$ C×(15min~30min), bulk type.

Precautions

- 1. Avoid exposure to moisture at all times during transportation or storage.
- 2. Anti-Static precaution must be taken when handling GaN, InGaN, and AllnGaP products.
- 3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
- 4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
- 5. Avoid direct contact with the surface through which the LED emits light.
- 6. If possible, assemble the unit in a clean room or dust-free environment.

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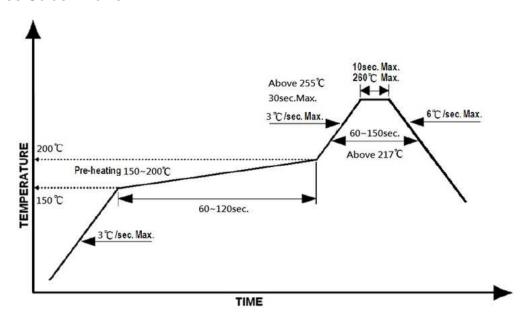


Reflow Soldering

Recommend soldering paste specifications:

- 1. Operating temp.: Above 217 °C ,60~150 sec.
- 2. Peak temp.:260 °C Max.,10sec Max.
- 3. Reflow soldering should not be done more than two times.
- Never attempt next process until the component is cooled down to room temperature after reflow.
- 5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



Reworking

- Rework should be completed within 5 seconds under 260℃.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

Cleaning

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100°C max, <3min

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Cautions of Pick and Place

- Avoid stress on the resin at elevated temperature.
- Avoid rubbing or scraping the resin by any object.
- Electric-static may cause damage to the component. Please ensure that the equipment is properly grounded. Use of an ionizer fan is recommended.

Revise History

Rev.	Descriptions	Date	Page
1.0	-	10/30/2024	-
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